



Layer	Stack up	Description	Impedance ID	Base Thickness	Finish Thickness	Mask Thickness	Type	ϵ_r	
		Screened Ident					Ident		
		Liquid PhotoImageable Mask				0.984	SolderMask	4.000	
1		Copper Foil	1, 2	1.378	1.378		Copper		
		PrePreg 1651		5.906	5.906		Dielectric	4.200	
2				1.378	1.378				
		FR4		47.244	47.244			4.300	
3				1.378	1.378				
		PrePreg 1651		5.906	5.906		Dielectric	4.200	
4		Copper Foil	3, 4	1.378	1.378		Copper		
		Liquid PhotoImageable Mask				0.984	SolderMask	4.000	
		Screened Ident					Ident		

Copper Thickness = 5.512 | Dielectric Thickness = 59.055 | Overall Processed Thickness = 64.567

Impedance ID	Structure Name	Impedance Signal Layer	Ref. Plane 1 in Layer	Ref. Plane 2 in Layer	Lower Trace Width	Trace Separation	Ground Strip Separation	Target Impedance	Calculated Impedance	Tol (+/- %)	
1	Coated Microstrip 1B	1	2	0	9.700	0.000	0.000	50.000	49.840	10.000	
2	Edge Coupled Coated Microstrip 1B	1	2	0	7.000	8.500	0.000	100.000	99.870	10.000	
3	Coated Microstrip 1B	4	3	0	9.700	0.000	0.000	50.000	49.840	10.000	
4	Edge Coupled Coated Microstrip 1B	4	3	0	7.000	8.500	0.000	100.000	99.870	10.000	

Notes

StackName: 2-Layer	Version:	Revision:	Modification:	Date of Revision:	Editor		
Date: 11-02-2023	Associated Documents:					Page 2/2	
Author:							
Department:							
Site:							